

STRUCTURE AND METHOD FOR WIRING TRANSLATION BETWEEN GRIDS
WITH NON-INTEGRAL PITCH RATIOS IN CHIP CARRIER MODULES

ABSTRACT

5 A jogging structure for translating wiring connections from points in a first grid to
corresponding points in a second grid in a chip carrier module is disclosed. In an
exemplary embodiment, the structure includes a first translation layer, coupled to the first
grid, the first translation layer translating the first grid in an x-axis direction. A second
translation layer is coupled to the first translation layer, the second translation layer for
translating said wiring connections from the first grid in a y-axis direction, the y-axis
10 direction being orthogonal to the x-axis direction. The second translation layer is further
coupled to the second grid.